

What is Claimed is:

1. A photoresist polymer remover composition comprising:
 - (a) 5% to 15% of sulfuric acid based on the total weight of said composition;
 - (b) 1% to 5% of hydrogen peroxide or 0.0001% to 0.05% of ozone based on the total weight of said composition;
 - (c) 0.1% to 5% of acetic acid based on the total weight of said composition;
 - (d) 0.0001% to 0.5% of ammonium fluoride based on the total weight of said composition; and
 - (e) remaining amount of water.
2. The photoresist polymer remover composition according to claim 1, comprising:
 - (a) 7% to 10% of sulfuric acid based on the total weight of said composition;
 - (b) 2% to 4% of hydrogen peroxide or 0.0002% to 0.001% of ozone based on the total weight of said composition;
 - (c) 0.5% to 2% of acetic acid based on the total weight of said composition;
 - (d) 0.01% to 0.05% of ammonium fluoride based on the total weight of said composition; and
 - (e) remaining amount of water.
3. The photoresist polymer remover composition according to claim 1, wherein the composition is further characterized as a dry etching cleaner.